





UV Laser Cutting and Drilling Machine





Characteristics:

- 1. **High-performance UV Laser Source:** Use diode-pumped UV Laser source with high beam quality, high peak power and short pulse width, which can achieve "cold "processing that ensures the stability and quality.
- 2. Optimized Optical System: Optimized optical transmission system with low power consumption, small focused spot size, high beam quality to ensure the reliability and consistency of the quality.
- High-precision Motion System: Imported high precision linear motion module and control module, ensure the device
 has high position accuracy and repeatability.
- 4. Machine vision system: With two high resolution CCD cameras, combing self-developed image processing algorithm to ensure accuracy and efficiency of the processing.
- 5. Natural Granite Platform: Natural and massive granite base reduces the inertia vibration of the table during start-up, shut-down and acceleration. At the same time, it maintains structure size long-term stability.
- **6. Software:** With intelligent processing platform software-Thetalaser, which is a smart laser micromachining application platform, user-friendly easy to operate and enabling customized software modules.

Application Range:

- Drilling and de-panelizing flexible printed circuit board, rigid printed circuit board, flexible-rigid printed circuit board, and chip substrate package.
- De-panelizing assembled flexible or rigid circuits.
- Precisely cutting and scribing ceramics with the thickness within 2.0mm.
- Precisely cutting thin copper foil, pressure sensitive adhesive, PP, acrylic sheet, polyimide film, etc.

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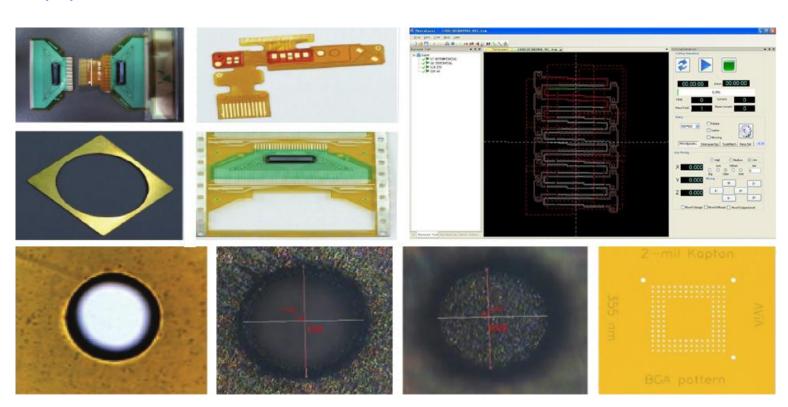
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- Precisely cutting ITO thin film, glass, organic thin film, special metal sheet, wafer and sapphire, etc.
- Support Roll to Roll Cutting way.(option)

Specification: (3Sigma)

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Model	TLS-G8200
Cutting Area	500mm×500mm×50mm(Customizable)
Accuracy of X/Y	<±3µm
Repeatability of X/Y Axis	±1µm
X/Y moving speed	800mm/s max
Laser Wavelength	355nm
Laser Repetition Rate	30-130KHz
Operating Temperature	23±3°C
Operation Humidity	20%~70%RH(no dew)
Input Data Format	Gerber, DXF, HPGL, Sieb&Meyer, Excellon, PCB
Input Voltage	3Ф,380VAC±10%, 50/60Hz, 15A
Power Consumption	3.0KW
Compressed Air Pressure	0.7~0.8MPa
Machine Size(LxWxH)	2125mm×1840mm×1800mm
Weight	3500Kg
Origin	China

Sample picture:



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